# **Energy Efficient Computing for Science**

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### The Problem



#### Where we are



#### **How we got here – 5 Decades of Innovations**



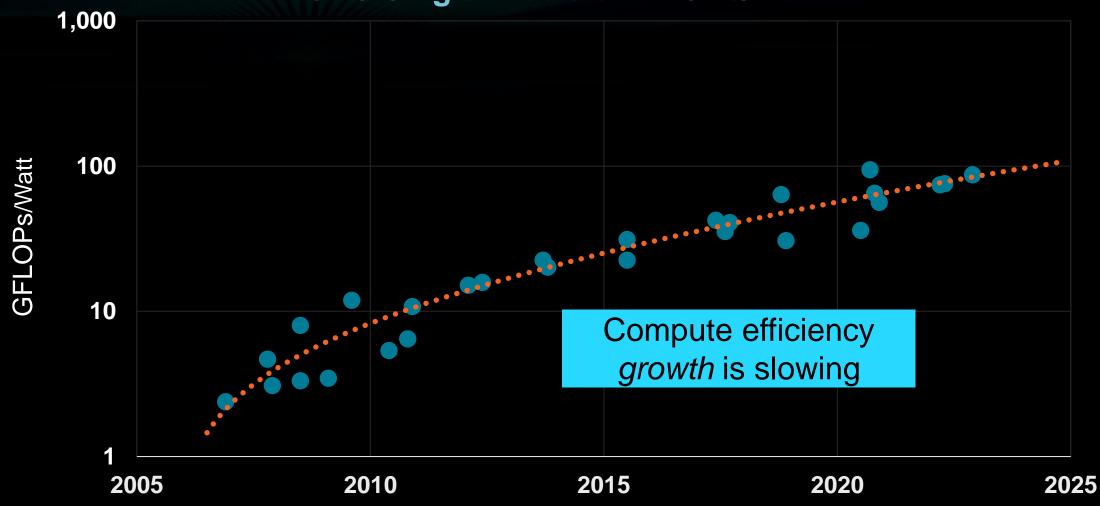
> 2000 times faster

> 3000 times smaller

Analysis based on comparing an AMD AM9080 processor running at 2MHz to an AMD Ryzen 9 7950X with base clock frequency of 4.5GHz.

#### **Trends – GPU Efficiency**

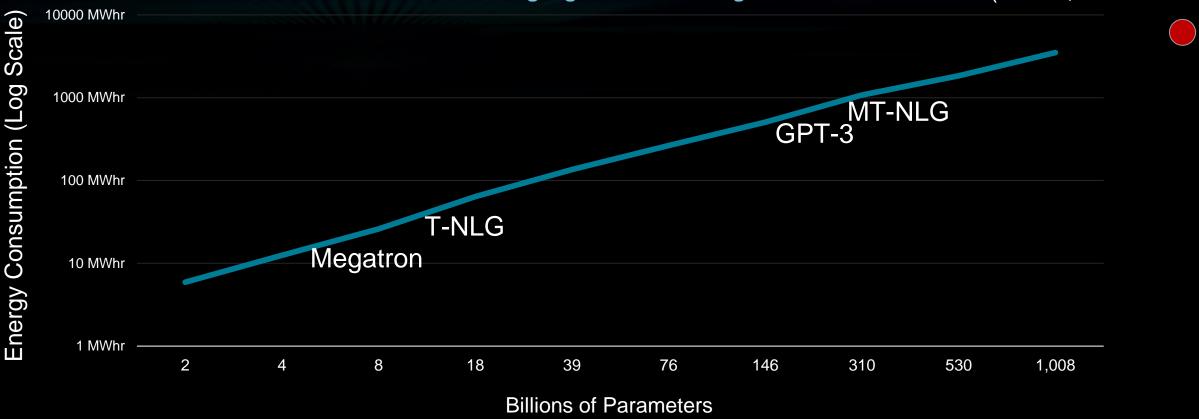






#### **Need Continues to Increase**

GPT-4 (~1.7T, 3500MWh)



**Language Model Training** 

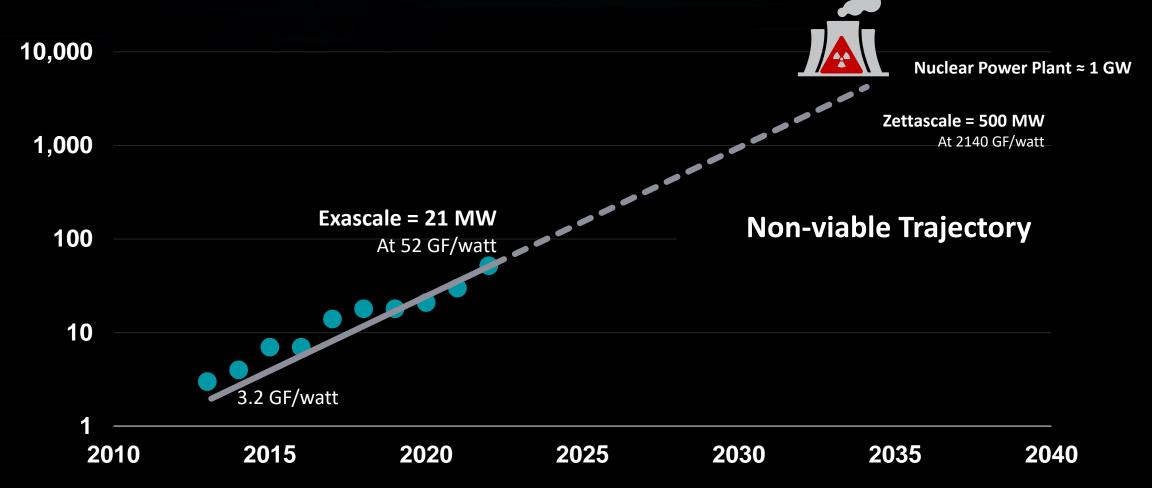
Exponentially growing model sizes drive immense growth in energy for training.

The upper bound on training requirements is yet to be determined.



#### **Supercomputer Energy Use Trajectory**



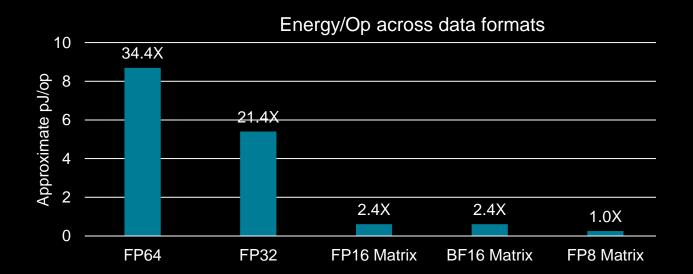


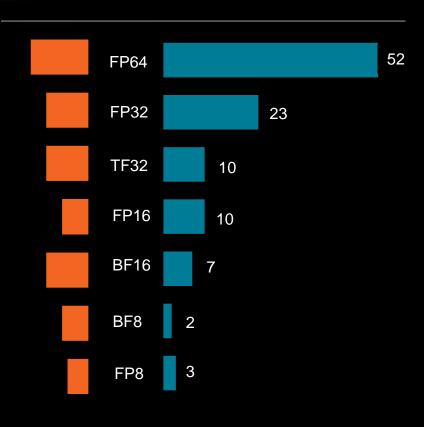
### The Opportunity



#### Flop Power and Reduced Precision

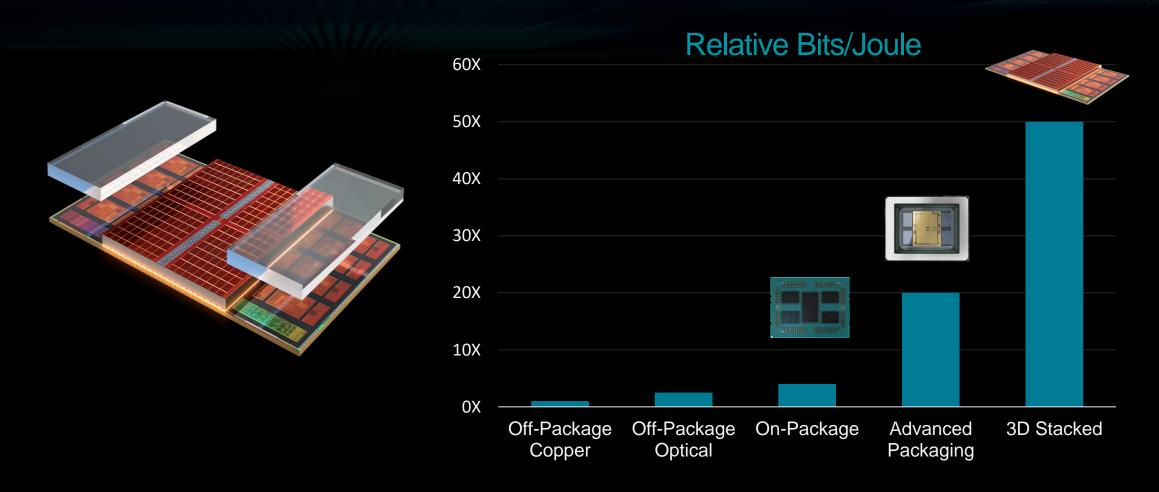
- New algorithms to exploit reduced precision arithmetic offer orders of magnitude improved compute efficiency
  - 32b  $\rightarrow$ 16b $\rightarrow$ 8b  $\rightarrow$ 6b and 4b formats
- Dedicated matrix math datapaths increase efficiency further







#### **3D Chiplets and Communication Power**

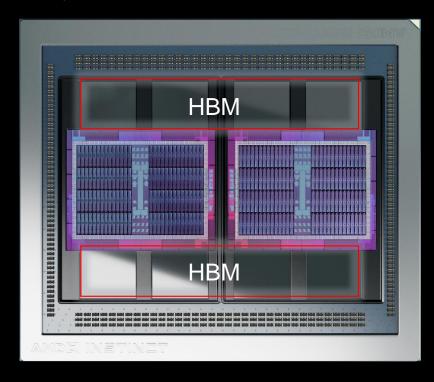


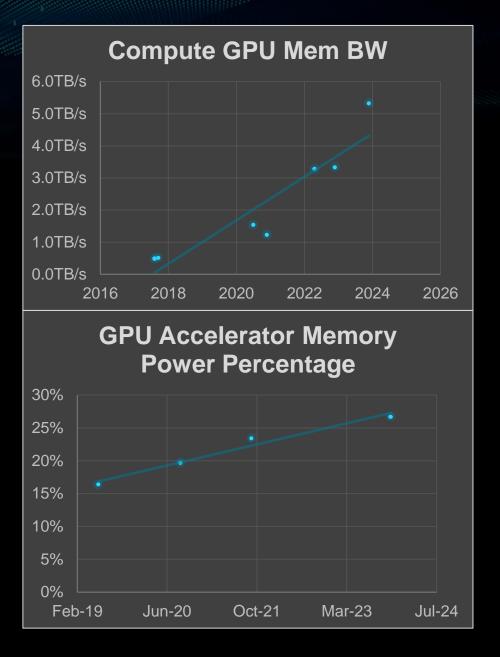
Advanced Packaging Provides up to a 50x Reduction in Communication Power



#### **Thirst for Memory Bandwidth**

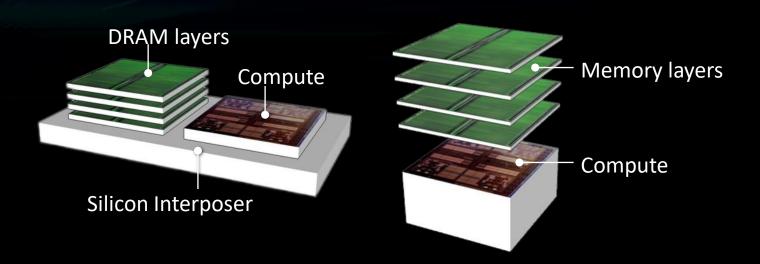
- High bandwidth memory feeds the compute engine providing a key element of performance gains
- Limited efficiency gains combine with demand growth result in higher percentage of power for memory

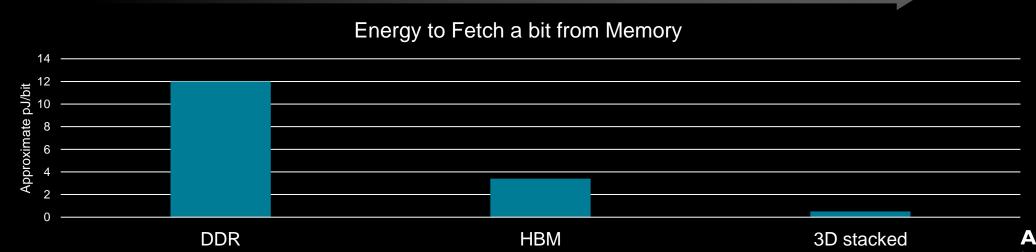




#### **Reducing Memory Power**

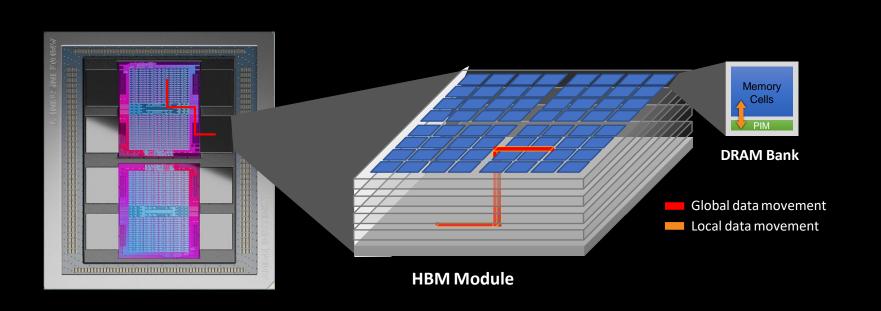


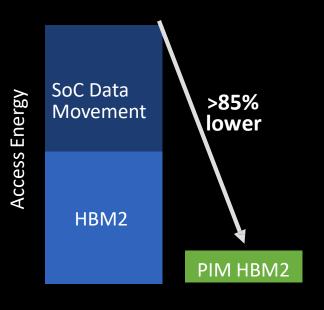




#### **Processing in Memory**

 Key algorithmic kernels can be executed directly in memory, saving precious communication energy

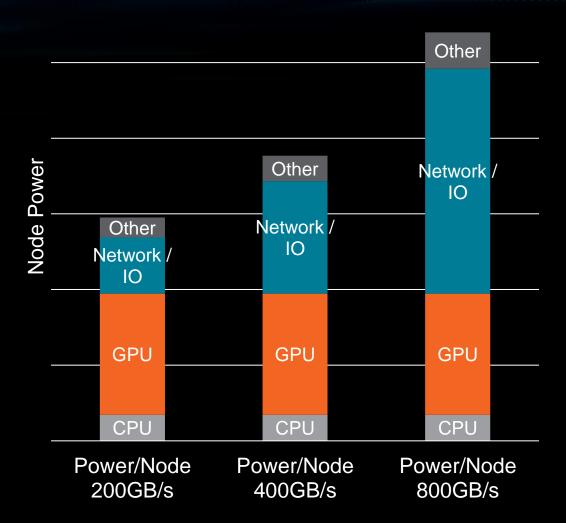






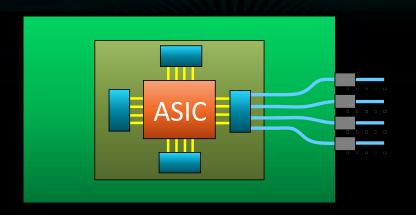
#### **System Power by Function**

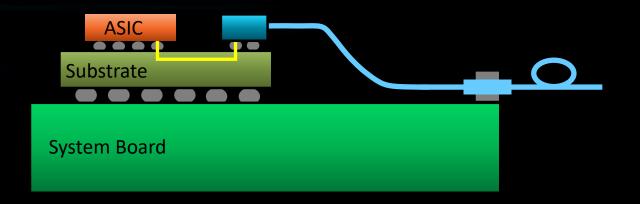
- Historical trends for model growth and system requirements point to a doubling of bandwidth every two years
- Even if compute power can be contained, network power will grow
- In two generations, we expect network+IO power to dominate the compute node
- Lower power solutions needed





#### **Optical Communication for Energy Efficient Networks**





Co-packaged optics can provide a path forward

Reach and BW
density reduces
switch and re-timer
power

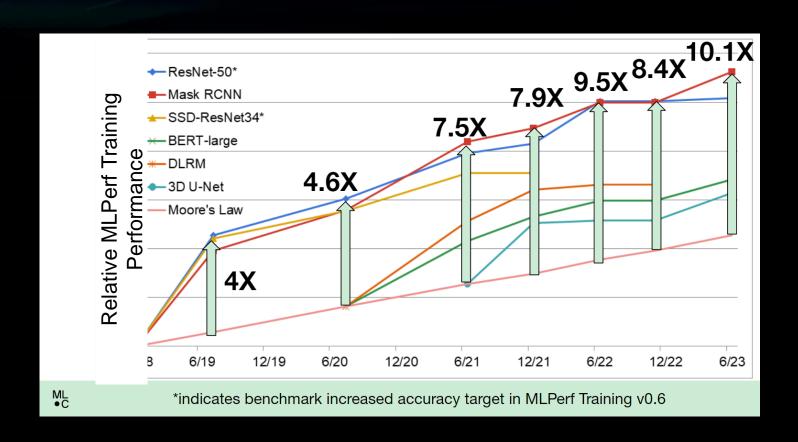
Path to ~1 pJ/bit and optical circuit switches for greater efficiency

Tight integration of optical transceivers to compute die is a key to efficiency



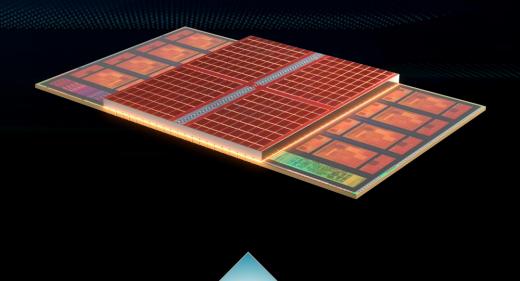
#### **Software-Hardware Co-Design**

 Combination of algorithms and architecture have been and will continue to be a critical lever



## Meeting the Challenge Requires Holistic Innovation

- Hardware architecture
- Advanced packaging
- New interconnects and memory
- System level integration
- Intelligent management
- And above all, algorithm-softwarehardware co-design





#### **Final Thought**





100+ MW

5,000,000

20W

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